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5. A solder resist composition to be used for manufacturing the multilayered printed circuit board according to claim 1,

wherein an inorganic filler is mixed with a paste containing a resin for a solder resist layer.

K3

10. (amended) The multilayered printed circuit board according to claim 7, wherein said solder resist layer contains an inorganic filler.

PA

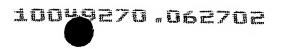
- 17. (amended) The multilayered printed circuit board according to claim 14, wherein said solder resist layer has a dielectric loss tangent of 0.01 or lower at 1 GHz.
- 18. (amended) The multilayered printed circuit board according to claim 14, wherein said solder resist layer is comprising a cycloolefin type resin.

ps

21. (amended) The multilayered printed circuit board according to claims 14, wherein said resin insulating layer is comprising a polyolefin type resin or a polyphenylene type resin.

bp

26. (amended) The multilayered printed circuit board according to claim 23, wherein said solder resist layer has a dielectric constant of 3.0 or lower at 1 GHz.



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27. (amended) The multilayered printed circuit board according to claim 24, wherein said polyphenylene ether resin is a thermosetting type polyphenylene ether resin and/or thermoplastic type polyphenylene ether resin.

28. (amended) The multilayered printed circuit board according to claim 23, wherein said resin insulating layer is comprising a polyphenylene ether resin.

AT

35. (amended) The multilayered printed circuit board according to claims 30, wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.